

RB521S-30

Rev.C Oct.-2024

描述 / Descriptions

SOD-523 塑封封装 肖特基二极管。
Schottky Diode in a SOD-523 Plastic Package.

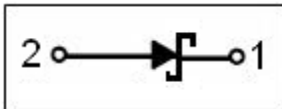
特征 / Features

低正向电压降，无卤产品。
Low forward voltage drop, HF Product.

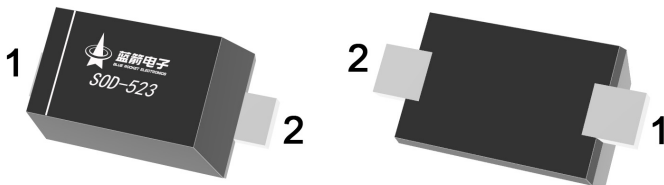
用途 / Applications

一般用途。
General purpose.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN1: Cathode

PIN2: Anode

印章代码 / Marking

| Type number | Marking code |
|-------------|--------------|
| RB521S-30 | C |

极限参数 / Absolute Maximum Ratings(Ta=25°C)

| 参数 Parameter | 符号 Symbol | 数值 Rating | 单位 Unit |
|--|------------------|--------------|------------|
| Reverse Voltage | V _R | 30 | V |
| Forward Continuous Current | I _F | 200 | mA |
| Non-Repetitive Peak Forward Surge Current @t = 8.3ms | I _{FSM} | 1 | A |
| Power dissipation | P _D | 200 | mW |
| Junction Temperature | T _J | 125 | °C |
| Storage Temperature | T _{stg} | -55 to +125 | °C |

电性能参数 / Electrical Characteristics(Ta=25°C)

| 参数 Parameter | 符号 Symbol | 测试条件 Test Conditions | 数值 Rating | | | 单位 Unit |
|---------------------------|-----------------|-------------------------|--------------|-----|------|------------|
| | | | Min | Typ | Max | |
| Reverse Breakdown Voltage | V _{BR} | I _R =500μA | 30 | | | V |
| Forward Voltage | V _F | I _F =20mA | | | 0.37 | V |
| | | I _F =200mA | | | 0.60 | V |
| Peak Reverse Current | I _R | V _R =10V | | | 5.0 | μA |

电参数曲线图 / Electrical Characteristic Curve

Fig.1 Power Derating Curve

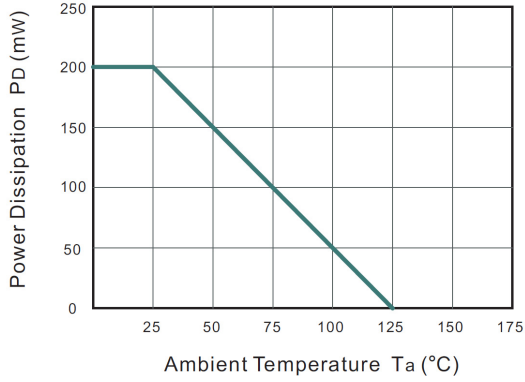


Fig.2 Typical Instantaneous Reverse Characteristics

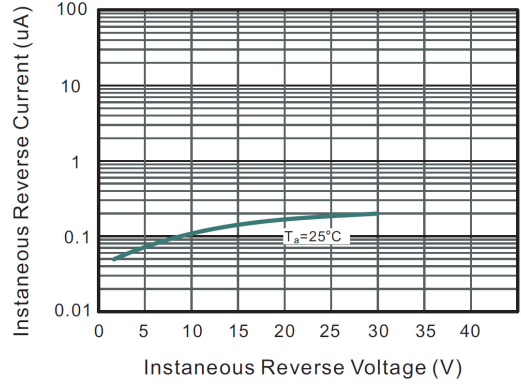
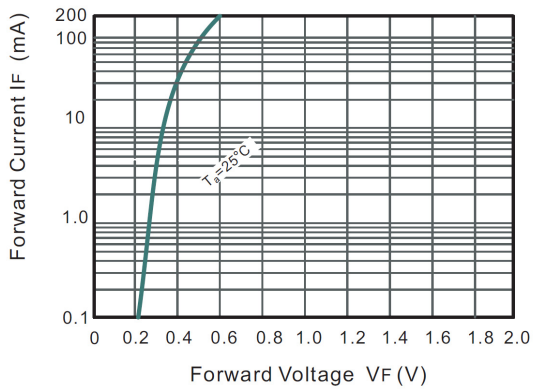
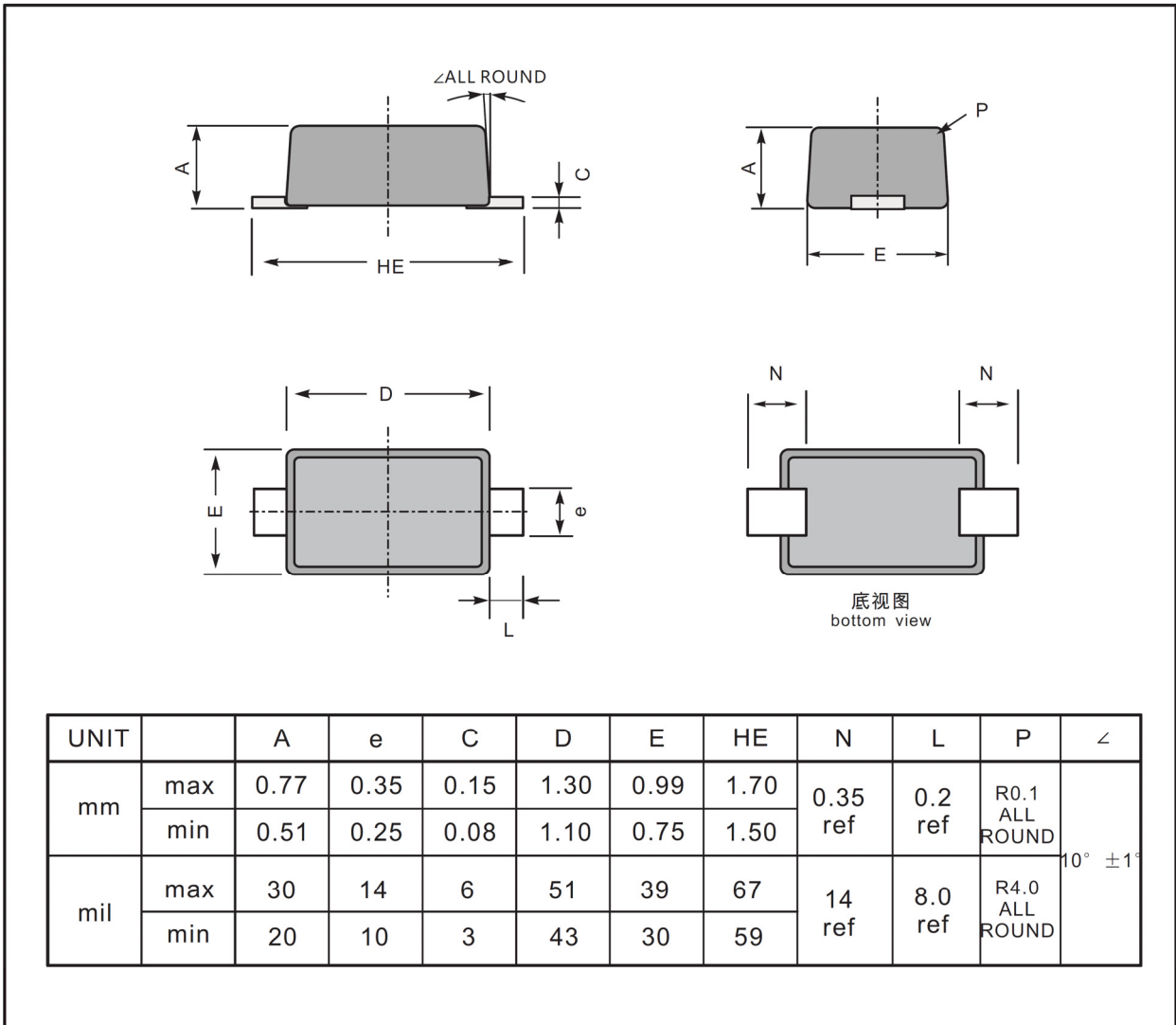


Fig.3 Typical Forward Characteristic

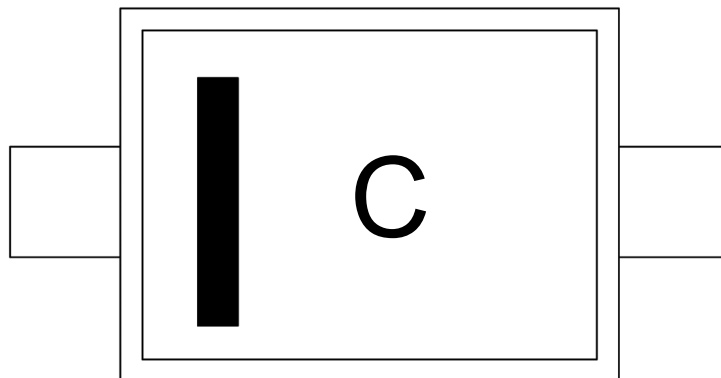


外形尺寸图 / Package Dimensions

SOD-523



印章说明 / Marking Instructions



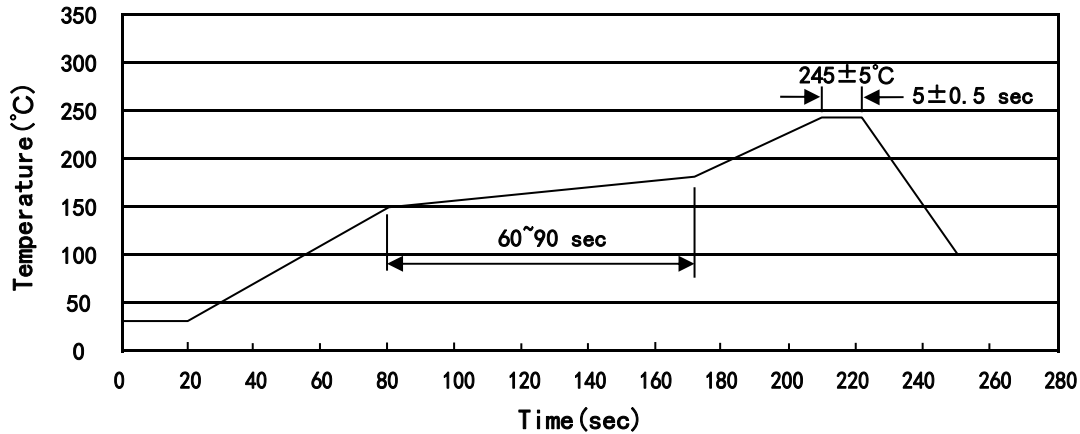
说明：

C： 为型号代码

Note:

C： Product Type Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150~180°C，时间 60~90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C 时间：10±1 sec. Temp.:260±5°C Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

| Package Type 封装形式 | Units 包装数量 | | | | | Dimension 包装尺寸 (unit: mm ³) | | |
|----------------------|--------------------|-------------------------|------------------------|------------------------------|------------------------|---|-------------|-------------|
| | Units/Reel 只/卷盘 | Reels/Inner Box 卷盘/盒 | Units/Inner Box 只/盒 | Inner Boxes/Outer Box 盒/箱 | Units/Outer Box 只/箱 | Reel | Inner Box 盒 | Outer Box 箱 |
| SOD-523 | 3,000 | 10 | 30,000 | 6 | 180,000 | 7" ×8 | 180×120×180 | 390×385×205 |

使用说明 / Notices